



**DISCO**

Kiru · Kezuru · Migaku Technologies



Grinding Wheels

# GS08 SERIES

## Grinding wheels enabling high quality grinding of SiC wafers



### Porous vitrified bond, fixed abrasive wheels resulting in high quality grinding of SiC wafers

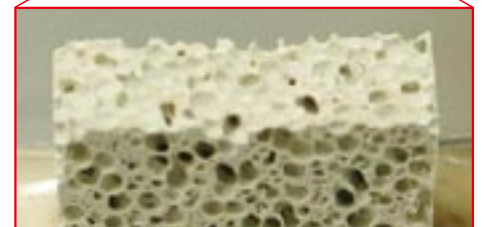
GS08 series grinding wheels employ a new porous vitrified bond with excellent swarf removal capability as well, the new bond feeds in the wheel coolant water in order to grind extremely hard SiC wafers. Grinding with a fixed abrasive produces a surface roughness approaching a polish. Grinding can be performed on tape mounted wafers making it unnecessary to use wafer carriers. The total process is much easier compared to a slurry processes.

- Grinding with a fixed abrasive results in a surface roughness approaching a polish
- Grinding can be performed on tape-mounted wafers for easy operation.
- Non-slurry process for a low environmental impact



### ■ Porous vitrified bond

The GS08 series employs an original porous vitrified bond.



### Applications

SiC, Al<sub>2</sub>O<sub>3</sub>, Si<sub>3</sub>N<sub>4</sub>, etc.

**Specifications**

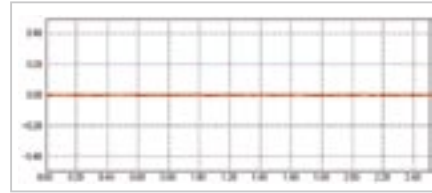
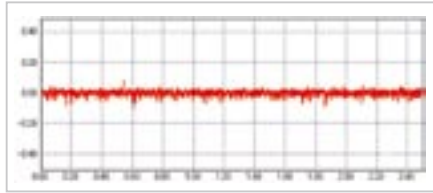
Wheel size	Tooth indication	Shape	Arrangement
200	SR	Segment	Circular

(mm)

**GS08 - SE0126 200 × 3.5 W × 4.5 T - SR**

Tooth type	Tooth width	Tooth height
SE0126 Standard	3.5	4.5
SA0135 Fine mesh	3.5	3.5

(mm) (mm)

**Experimental Data****Surface roughness when grinding SiC**

Wheel used	SE0126 (Standard)	SA0135 (Fine mesh)
Ra (μm)	0.011	0.001
Ry (μm)	0.115	0.009

Workpiece : ø3" SiC wafer  
 Measurement system : Contact high-resolution surface profile measurement system

**When ordering**

Please contact a DISCO representative with your product needs such as type, wheel size, and quantity.

When you place the first order with us, please explain application information such as materials to grind, sizes, machine, type, and other specification.

We are ready to help you to determine which is our most appropriate product type for your application.

Due to improvements in our products, it is possible that product specifications may be changed without advanced notice.  
 Please confirm the product specifications with a DISCO representative.

**To use these DISCO wheels safely...**

Please read carefully and follow the instructions below to prevent any accidents or injuries.

- USE a safety cover (nozzle case, cover), equipped as a standard accessory, to avoid injury.
- DO NOT EXCEED the maximum rpm if it is specified.
- FOLLOW the instruction manual of the machine to mount wheel properly.
- DO NOT DROP OR HIT wheels. this may cause wheel breakage or injury.
- Always CHECK the wheel for chipping or any other wheel damage before starting to use the wheel. DO NOT USE the wheel if there is any damage.
- READ the operation manual of the cutting/ grinding equipment before use.
- DO NOT USE a wheel with a modified or customized equipment.
- DO NOT USE a wheel that has a different size from the one recommended for your machine.
- DO NOT USE a wheel for any other purpose than Grinding, Cutting, or Polishing.
- Always USE water or coolant to prevent wheel breakage.

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